



## HOSTAFORM® C 27021 XAP®2 LS HOSTAFORM®

Polyacetalcopolymer Easy flow injection molding grade with reduced emissions especially for automotive interior application. With Improved UV resistance Burning rate according to FMVSS 302 < 100 mm/min (1 mm thickness) Emission according to VDA 275 < 5 mg/kg.

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Product information			
Resin Identification	POM		ISO 1043
Part Marking Code	>POM<		ISO 11469
Rheological properties			
Melt volume-flow rate	24	cm <sup>3</sup> /10min	ISO 1133
Temperature	190	°C	
Load	2.16	kg	
Moulding shrinkage, parallel	2.1	%	ISO 294-4, 2577
Moulding shrinkage, normal	2.0	%	ISO 294-4, 2577
Typical mechanical properties			
Tensile modulus	2750	MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	64	MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	7.5	%	ISO 527-1/-2
Nominal strain at break	17	%	ISO 527-1/-2
Flexural modulus	2600	MPa	ISO 178
Tensile creep modulus, 1h	2400	MPa	ISO 899-1
Tensile creep modulus, 1000h		MPa	ISO 899-1
Charpy impact strength, 23°C		kJ/m²	ISO 179/1eU
Charpy impact strength, -30°C		kJ/m²	ISO 179/1eU
Charpy notched impact strength, 23°C		kJ/m²	ISO 179/1eA
Charpy notched impact strength, -30°C		kJ/m²	ISO 179/1eA
Poisson's ratio	0.37 <sup>[C]</sup>		
[C]: Calculated			
Thermal properties			
Melting temperature, 10°C/min	166	°C	ISO 11357-1/-3
Coefficient of linear thermal expansion	110	E-6/K	ISO 11359-1/-2
(CLTE), parallel			
Coefficient of linear thermal expansion (CLTE), normal	110	E-6/K	ISO 11359-1/-2
Electrical properties			
Relative permittivity, 100Hz	4		IEC 62631-2-1
Relative permittivity, 1MHz	4	<b>-</b> .	IEC 62631-2-1
Dissipation factor, 100Hz		E-4	IEC 62631-2-1
Dissipation factor, 1MHz		E-4	IEC 62631-2-1
Volume resistivity		Ohm.m	IEC 62631-3-1
Surface resistivity	1E14	_	IEC 62631-3-2
Electric strength	600	kV/mm	IEC 60243-1 IEC 60112
Comparative tracking index	000		IEC 00112

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### Physical/Other properties

Humidity absorption, 2mm	0.2 %	Sim. to ISO 62
Water absorption, 2mm	0.65 %	Sim. to ISO 62
Density	1410 kg/m³	ISO 1183

### Injection

Drying Recommended	no	
Drying Temperature	100	°C
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	190	°C
Min. melt temperature	180	°C
Max. melt temperature	200	°C
Screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	100	°C
Min. mould temperature	80	°C
Max. mould temperature	120	°C
Hold pressure range	60 - 120	MPa
Back pressure	4	MPa

#### Characteristics

Processing Injection Moulding

Delivery form Granules

Special characteristics U.V. stabilised or stable to weather, High Flow, Low emissions

### Additional information

Injection molding Preprocessing

To achive low emission values pre drying using a recirculating air dryer (100 to  $120 \, ^{\circ}\text{C}$  / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,1 %

**Processing** 

Standard injection moulding machines with three phase (15 to 25 D) plasticating screws will fit.

Postprocessing

Conditioning e.g. moisturizing is not necessary.

Processing Notes Pre-Drying

recommended

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### **Automotive**

OEM STANDARD ADDITIONAL INFORMATION

Mercedes-Benz DBL5404 BQF

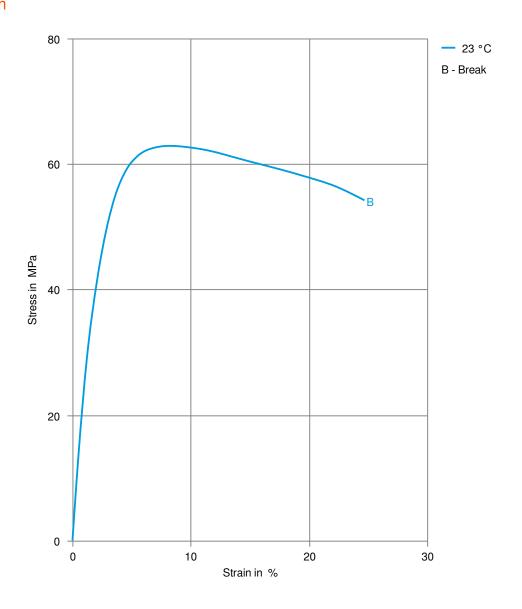
Mercedes-Benz DBL5410

Renault No Spec, Special Part Approval, See Your CE

Account Manager.

VW Group TL 524 76

### Stress-strain



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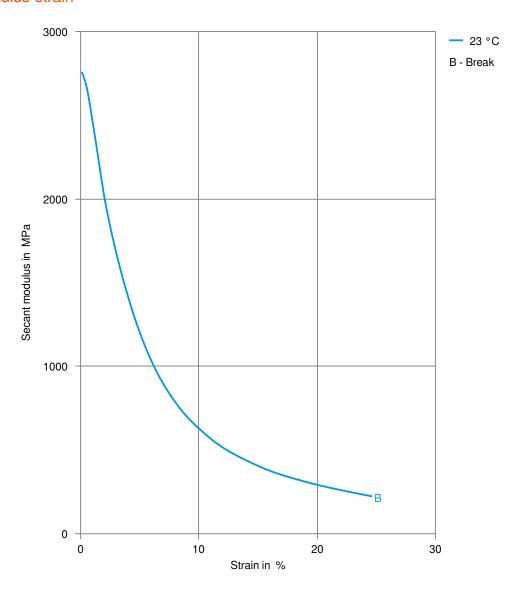
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## HOSTAFORM® C 27021 XAP®2 LS HOSTAFORM®

#### Secant modulus-strain



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